DQD (R-PWSON-N12)

PLASTIC SMALL OUTLINE NO-LEAD

2.60
2.40

1

7

1.45
1.25

1

0.80
0.70

0.05
0.00

Sealing Plane

0.05
C

0.05
C

0.20 Nominal
Lead Frame

NOTES:
A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M–1994.
B. This drawing is subject to change without notice.
C. SON (Small Outline No-Lead) package configuration.
D. The package thermal pad must be soldered to the board for thermal and mechanical performance.
E. See the additional figure in the Product Data Sheet for details regarding the exposed thermal pad features and dimensions.

Pin 1 identifiers are located on both top and bottom of the package and within the zone indicated.
The Pin 1 identifiers are either a molded, marked, or metal feature.
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